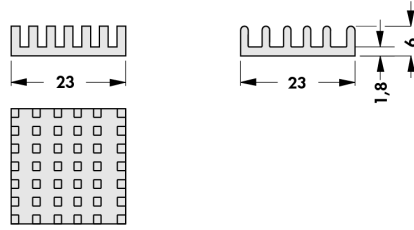
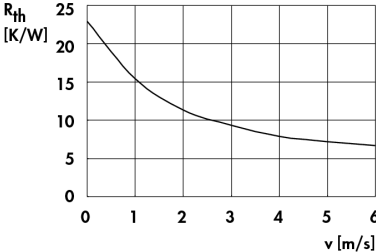
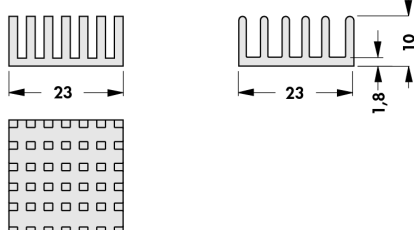
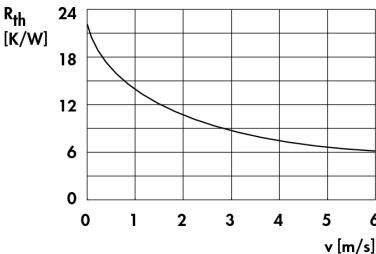
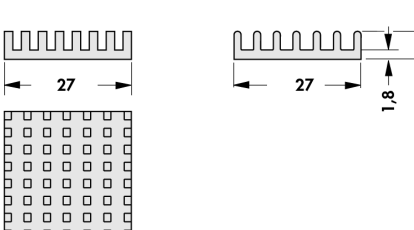
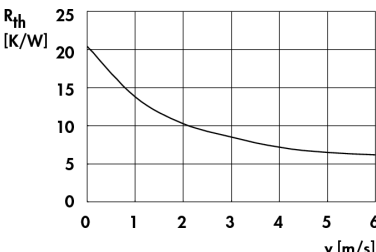
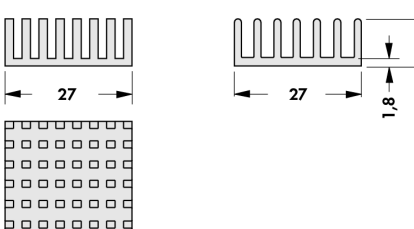
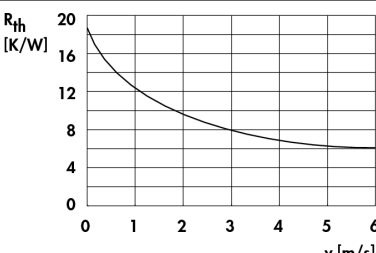
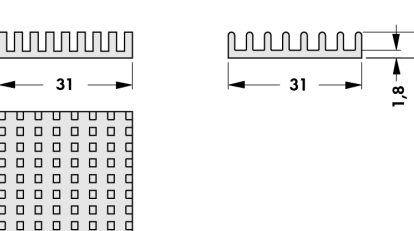
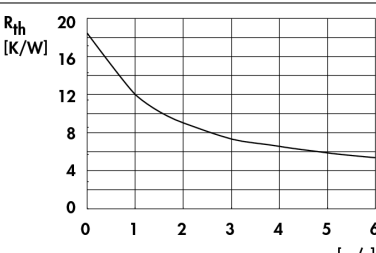
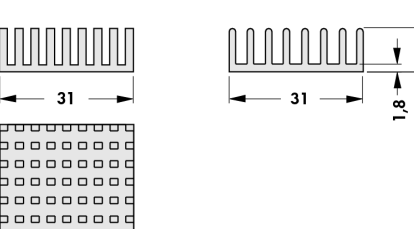
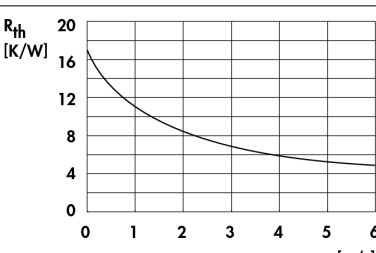


## Heatsinks for PGAs and BGAs

|   |   |   |
|---|---|---|
| <p><b>art. no.</b></p> <p><b>ICK BGA 23 x 23</b><br/>WLF ... 23 x 23</p>      |    |    |
| <p><b>art. no.</b></p> <p><b>ICK BGA 23 x 23 x 10</b><br/>WLF ... 23 x 23</p> |    |    |
| <p><b>art. no.</b></p> <p><b>ICK BGA 27 x 27</b><br/>WLF ... 27 x 27</p>      |   |   |
| <p><b>art. no.</b></p> <p><b>ICK BGA 27 x 27 x 10</b><br/>WLF ... 27 x 27</p> |  |  |
| <p><b>art. no.</b></p> <p><b>ICK BGA 31 x 31</b><br/>WLF ... 31 x 31</p>      |  |  |
| <p><b>art. no.</b></p> <p><b>ICK BGA 31 x 31 x 10</b><br/>WLF ... 31 x 31</p> |  |  |

Thermal conduct. foil WLFT 404/405 → E 5  
 Thermal conductive glue → E 14  
 Thermal conductive paste → E 12  
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27  
 Mounting material for semiconduct. → E 34 - 38  
 Hole pattern → A 21  
 Technical introduction → A 2 - 7